

**LTM8050-BGA 70L,15mm X 9mm X 4.92mm (TABLE OF MATERIAL DECLARATION)**
*The LTM8050 is RoHS compliant per EU RoHS Directive 2003/95/EC.*

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1480	Barium Compounds	7727-43-7	0.00379	2.56
				Bismaleimide/Triazine/Resin/Filler Substances (Silica Crystalline)	105391-33-1, 1156-51-0/9003-36-5/21645-51-2, non-disclosure	0.02824	19.08
				Copper Metal	7440-50-8	0.08392	56.69
				Copper Compounds	147-14-8	0.00003	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00001	0.01
				Gold metal or alloy	7440-57-5	0.00022	0.15
				Nickel	7440-02-0	0.00104	0.70
				Zinc	7440-66-6	0.00016	0.11
				Continuous Filament Fiber Glass	65997-17-3	0.02219	14.99
				Acrylic Resin	non-disclosure	0.00721	4.87
				Epoxy Resin	non-disclosure	0.00003	0.02
				Chromium(III) Oxide	1308-38-9	0.00001	0.00
				Silica Amorphous	7631-86-9	0.00008	0.05
				Talc;not containing fiber like asbestos	14807-96-6	0.00044	0.30
				Aromatic carbonyl compounds	non-disclosure	0.00041	0.28
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium caobonate	471-34-1	0.00000	0.00
				Amine compounds	non-disclosure	0.00005	0.04
				Leveling agent and others	non-disclosure	0.00016	0.11
2	Solder Paste	Alloy	0.0900	Sn	7440-31-5	0.08546	95.00
				Sb	7440-36-0	0.00450	5.00
3	Passive/Active Components		0.6638	Iron Powder (Fe)	7439-89-6	0.48443	72.98
				Copper (Cu)	7440-50-8	0.13350	20.11
				Nickel (Ni)	7440-02-0	0.00549	0.83
				Tin (Sn)	7440-31-5	0.00517	0.78
				Ceramic (Ba) Compounds	12047-27-7	0.03521	5.30
4	Active Ics	Silicon	0.0041	Silicon	7440-21-3	0.00411	100.00
5	Wire	Gold	0.0002	Au	7440-57-5	0.00022	99.99
6	Solder Ball	SAC305	0.1191	Sn	7440-31-5	0.11489	96.50
				Ag	7440-22-4	0.00357	3.00
				Cu	7440-50-8	0.00060	0.50
7	Encapsulation	Epoxy Resin	0.8275	Fused Silica	60676-86-0	0.63885	77.20
				Epoxy Resin	non-disclosure	0.07365	8.90
				Phenol Resin	non-disclosure	0.07365	8.90
				Crytalline Silica	14808-60-7	0.02483	3.00
				Carbon Black	1333-86-4	0.00414	0.50
				Metal Hydroxide	non-disclosure	0.01241	1.50
Total Package Weight			1.8527				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts